

## C1206X152M2TACTU

Aliases (C1206X152M2TAC7800)

SMD Comm X8G HT150C Flex, Ceramic, 1,500 pF, 20%, 200 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1206, 1.5 mm



General Information		
Series	SMD Comm X8G HT150C Flex	
Style	SMD Chip	
Description	SMD, MLCC, High Temperature, Ultra-Stable	
Features	High Temperature, Ultra-Stable	
RoHS	Yes	
Termination	Flexible Termination	
Marking	No	
AEC-Q200	No	
Typical Component Weight	20 mg	
Shelf Life	78 Weeks	
MSL	1	

Dimensions		
Chip Size	1206	
L	3.3mm +/-0.4mm	
W	1.6mm +/-0.35mm	
Т	0.9mm +/-0.20mm	
S	1.5mm MIN	
В	0.6mm +/-0.25mm	

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Packaging Specifications	

Specifications		
Capacitance	1,500 pF	
Measurement Condition	1 kHz 1.0Vrms	
Tolerance	20%	
Voltage DC	200 VDC	
Dielectric Withstanding Voltage	500 VDC	
Temperature Range	-55/+150°C	
Temp. Coefficient	X8G	
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms	
Dissipation Factor	0.1% 1 kHz 1.0Vrms	
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours	
Insulation Resistance	100 GOhms	

Packaging	T&R, 180mm, Plastic Tape	Applied (TCC)
Packaging Quantity	4000	Dissipation Factor
		Aging Rate

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